

Please note that Cypress is an Infineon Technologies Company.

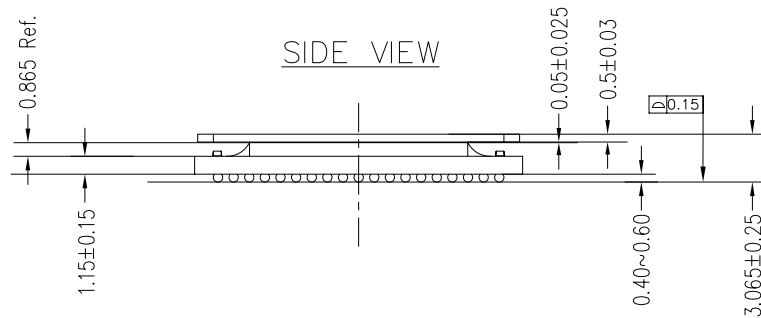
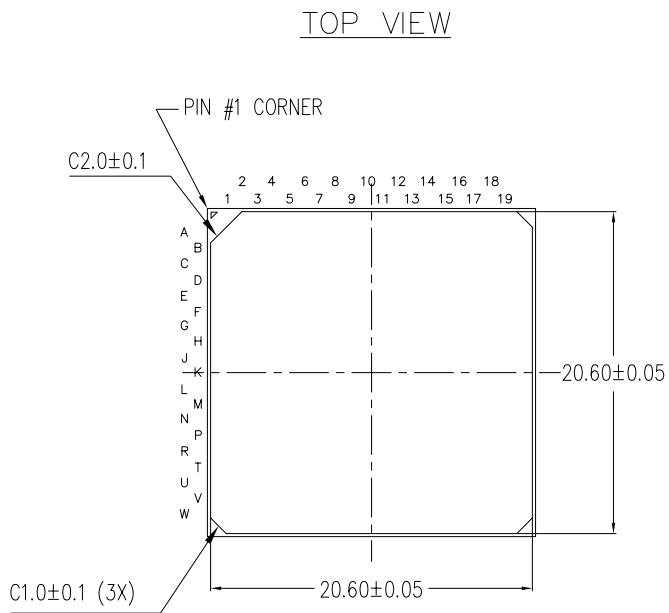
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

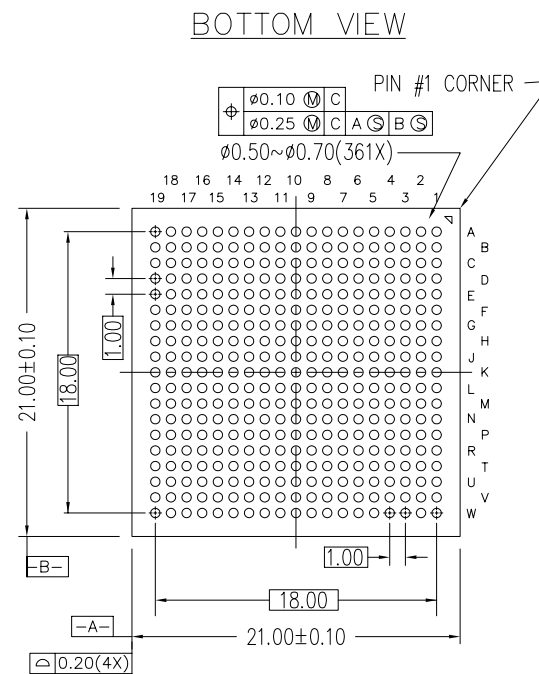
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.




NOTES:

SOLDER BALL DIAMETER: 0.63
 SOLDER PAD TYPE: SOLDER MASK DEFINED (SMD)
 PACKAGE CODE: FR0AB
 PACKAGE WEIGHT: SEE CYPRESS PACKAGE MATERIAL DECLARATION
 DATASHEET (PMDD) POSTED ON CYPRESS WEB



ENGINEERING USE ONLY


 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 361L HFC-BGA 21X21X3.065 MM FR0AB	
SPEC. NO. 001-70320	REV. *C
SCALE 1:1	SHEET 1 OF 2

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PACKAGE
CODE(S)

FR0AB

Rev.	ECN No.	Origin of Change	Description of change
**	3291448	CS	New Release
*A	3442794	CS	UPDATED SIDE VIEW, PKG WEIGHT, ADDED BALL DIA, AND CHANGED PACKAGE CODE TO FR0AB.
*B	3691601	CS	REVISED TO MATCH NEW SUBSTRATE DESIGN
*C	4452344	CS	Sunset Review, Updated POD Template to align with spec requirements.

 <div style="display: inline-block; vertical-align: middle;"> <p>CYPRESS</p> <p>Company Confidential</p> </div>	
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<p>SPEC. NO.</p> <p>001-70320</p>	<p>REV.</p> <p>✱C</p>
<p>SCALE 1:1</p>	<p>SHEET 2 OF 2</p>

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SCALE 1:1

SHEET 2 OF 2